

ABSTRACT OF THE DISCLOSURE

A resin tape substrate with a semiconductor chip mounted thereon is put to an attachment area surface of a cavity bottom surface, and a plurality of suction
5 holes connected to a suction system are disposed in the attachment area surface, wherein the attachment area surface of the cavity is formed in a semiconductor resin mold, so that the molten resin given into the cavity does not flow into the back surface of the resin
10 tape substrate which is sucked on the attachment area surface in the mold.

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